

MULTIDIMENSIONAL ULTRASONIC TRANSDUCER ARRAYS

Abstract of the disclosure:

5 A two dimensional ultrasonic transducer array stack
is described which has a backing block of acoustically
absorbent material formed of alternating plates of backing
material and flex circuits adhesively bonded together.
The thickness of the plates establishes the elevational
10 dimension between the flex circuits and corresponds to the
elevational pitch of the two dimensional array. The
backing block may also be formed by photoetching
conductive traces directly on the plates of backing
material, which are then adhesively bonded together to
15 form the backing block.

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